

# DuPont™ PlasmaSolv® EKC245™

## Post-Etch Residue Remover

DuPont™ PlasmaSolv® EKC245™ post-etch residue remover is made with DuPont™ HDA® hydroxylamine technology for enhanced performance.

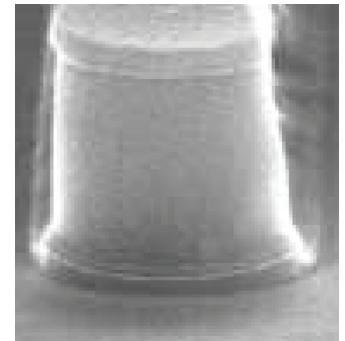
### Features

- High purity specifications for advanced wafer cleaning
- Removes residues from vias
- Cleans HBr etched polysilicon
- Removes residues after metal etch
- Operates below flashpoint
- Low evaporation rate at operating temperatures
- Does not require ultrasonics
- Rinses in water
- Compatible with automatic equipment
- Great device reliability and product yields
- Lowers via contact resistance
- Maintains gate oxide integrity
- Improves contact between metal layers
- Combines wet chemical processes
- Provides a safe chemical process
- Extends bath life, reduces air emissions, lowers factory operating cost
- Reduces equipment requirements
- Reduces cost of ownership by simplifying process
- Offers flexibility in process

### 0.5 μm Metal Lines

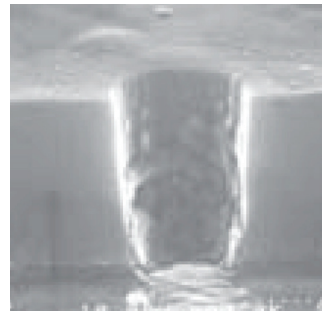


Before Clean

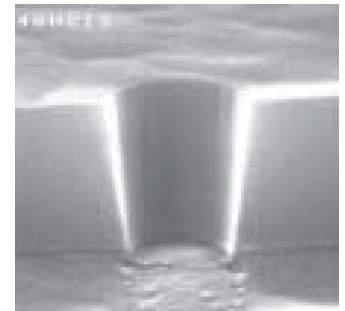


After Clean—Ox/Ti/AlCu/TiN 20 min at 65 °C

### 0.5 μm Via



Before Clean



After Clean—AlSiCu/TiN/TEOS 20 min at 65 °C



[ekctech.dupont.com](http://ekctech.dupont.com)

For more information on DuPont™ PlasmaSolv® EKC245™ or other DuPont products, please visit our website.

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**CAUTION:** Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement," H-50102-5 and "DuPont Policy Regarding Medical Applications" H-50103-5.

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K-23767-1 (05/19)